ZZ2 ■ These assemblies are ESD sensitive, ESD precautions shall be observed.
ZZ3 ■ These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.
ZZ4 ■ These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
ASSEMBLY VARIANT: [No Variations]

<table>
<thead>
<tr>
<th>PCB VIEWED FROM TOP SIDE</th>
<th>BOARD #: TIDA-00711</th>
<th>REV: E1</th>
<th>SUN REV: Not In VersionControl</th>
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<tr>
<td>M5 Assembly Top</td>
<td>TID #: TIDA-00711</td>
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PLOT NAME = Top Assembly Drawing
GENERATED: 12/9/2016 5:55:10 PM
TEXAS INSTRUMENTS
COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
ASSEMBLY VARIANT: [No Variations]

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<th>PCB VIEWED FROM BOTTOM SIDE</th>
<th>BOARD #: TIDA-00711</th>
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<td>M6 Assembly Bottom</td>
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PLLOT NAME = Bottom Assembly Drawing
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